



AF# 276

S/N 10/774,923

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Qing Ma	Examiner:	Roy K. Potter
Serial No.:	10/774,923	Group Art Unit:	2822
Filed:	February 9, 2004	Docket:	884.803US2
Title:	DIRECT BUILD-UP LAYER ON AN ENCAPSULATED DIE PACKAGE HAVING A MOISTURE BARRIER STRUCTURE		
Assignee:	Intel Corporation	Customer No.	21186

**NOTICE OF APPEAL FROM THE DECISION OF THE EXAMINER  
TO THE BOARD OF PATENT APPEALS AND INTERFERENCES**

**MAIL STOP AF**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

In compliance with 37 C.F.R. § 41.31(a)(1), Applicant hereby appeals to the Board of Patent Appeals and Interferences from the decision dated October 6, 2005, of the Examiner rejecting claims 20 and 29 of the above-identified patent application.

A Pre-Appeal Brief Request for Review is submitted herewith.

A request for an extension of time to respond to the Examiner's rejection is submitted herewith along with payment of the required extension fee.

Please charge the amount of \$500.00 in payment of the Notice of Appeal fee under 37 C.F.R. § 41.20(b)(1), as well as any additional required fees, to Deposit Account No. 19-0743.

Respectfully submitted,  
QING MA  
By her Attorneys,  
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Date Feb. 6, 2006 By Ann M. McCrackin  
Ann M. McCrackin  
Reg. No. 42,858

**CERTIFICATE UNDER 37 CFR 1.8:** The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: Mail Stop AF, Commissioner of Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 6th day of February, 2006.

Chris Hammond  
Name \_\_\_\_\_

Chris Hammond  
Signature \_\_\_\_\_

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